

SE4625

Complementary Enhancement-Mode MOSFET

Revision: A

General Description

Advanced trench technology to provide excellent RDS(ON), low gate charge and low operation voltage. This device is suitable for using as a load switch or in PWM applications.

- Low $R_{DS(on)}$
- Small Package Outline
- ESD protected

Features

For N-Channel MOSFET

- $V_{DS} = 12V$
- $R_{DS(ON)} = 28m\Omega @ V_{GS}=4.5V$

For P-Channel MOSFET

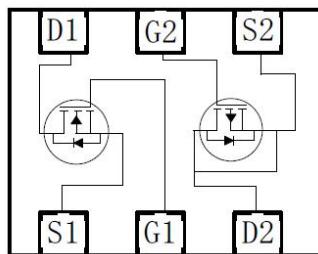
- $V_{DS} = -12V$
- $R_{DS(ON)} = 57m\Omega @ V_{GS}=-4.5V$

Pin configurations

See Diagram below



DFN2*2-6



Absolute Maximum Ratings

Parameter	Symbol	N-Channel	P-Channel	Units
Drain-Source Voltage	V_{DS}	12	-12	V
Gate-Source Voltage	V_{GS}	± 8	± 8	V
Drain Current	Continuous	5.1	-4.0	A
	Pulsed	17.6	-13.6	
Total Power Dissipation @TA=25°C	P_D	1.8		W
Operating Junction Temperature Range	T_J	-55 to 150		°C

Thermal Resistance

Parameter	Symbol	Value	Units
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	85	°C/W

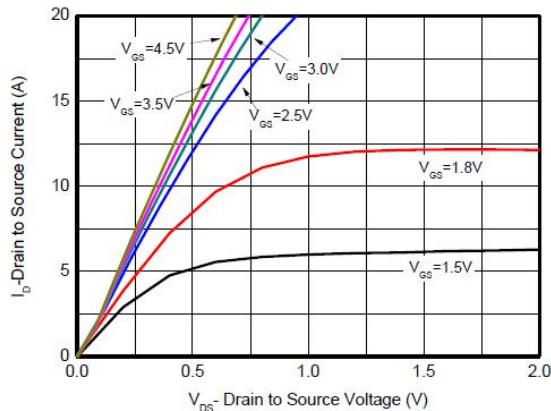
N-Channel Electrical Characteristics (TJ=25°C unless otherwise noted)

Electrical Characteristics (TJ=25°C unless otherwise noted)						
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS (Note 2)						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V	12			V
I _{DSS}	Drain to Source Leakage Current	V _{DS} =10V, V _{GS} =0V		1		μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±8V, V _{DS} =0V			±1	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA		0.7	1.2	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =4.5V, I _D =5.0A		28	46	mΩ
		V _{GS} =2.5V, I _D =4.6A		35	66	
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, f=1MHz	V _{DS} =6V,	469		pF
C _{oss}	Output Capacitance			125		pF
C _{rss}	Reverse Transfer Capacitance			95		pF
SWITCHING PARAMETERS						
Q _g	Total Gate Charge ²	V _{GS} =4.5V, I _D =6.5A	V _{DS} =10V,	5.38		nC
Q _{gs}	Gate Source Charge			1.3		nC
Q _{gd}	Gate Drain Charge			0.76		nC
t _{d(on)}	Turn-On Delay Time	V _{GS} =4.5V, V _{DS} =6V, R _{GEN} =1Ω I _D =5.2A	I _D =5.2A	20		ns
t _{d(off)}	Turn-Off Delay Time			48		ns
t _{d(r)}	Turn-On Rise Time			22		ns
t _{d(f)}	Turn-Off Fall Time			15		ns

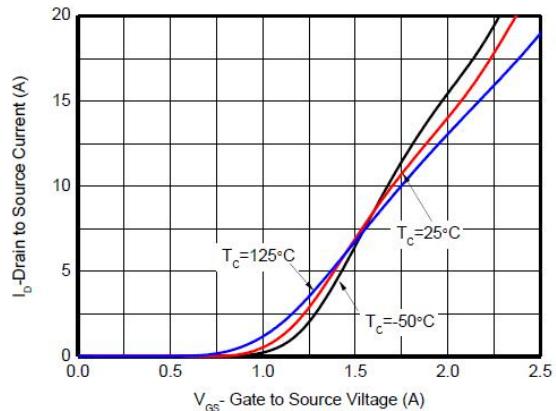
P-Channel Electrical Characteristics (TJ=25°C unless otherwise noted)

Electrical Characteristics (TJ=25°C unless otherwise noted)						
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS (Note 2)						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =-250μA, V _{GS} =0 V	-12			V
I _{DSS}	Drain to Source Leakage Current	V _{DS} =10V, V _{GS} =0V			-1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±8V, V _{DS} =0V			±1	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D =-250μA		-0.8	-1.2	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =-4.5V, I _D =-3.6A		57	75	mΩ
		V _{GS} =-2.5V, I _D =-3.2A		87	110	
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, f=1MHz	V _{DS} =-6V,	673		pF
C _{oss}	Output Capacitance			175		pF
C _{rss}	Reverse Transfer Capacitance			162		pF
SWITCHING PARAMETERS						
Q _g	Total Gate Charge ²	V _{GS} =-4.5V, I _D =-4.3A	V _{DS} =-10V,	6.56		nC
Q _{gs}	Gate Source Charge			1.2		nC
Q _{gd}	Gate Drain Charge			2.1		nC
t _{d(on)}	Turn-On Delay Time	V _{GS} =-4.5V, R _{GEN} =1Ω I _D =-3.8A	V _{DS} =-6V, I _D =-3.8A	30		ns
t _{d(off)}	Turn-Off Delay Time			62		ns
t _{d(r)}	Turn-On Rise Time			32		ns
t _{d(f)}	Turn-Off Fall Time			18		ns

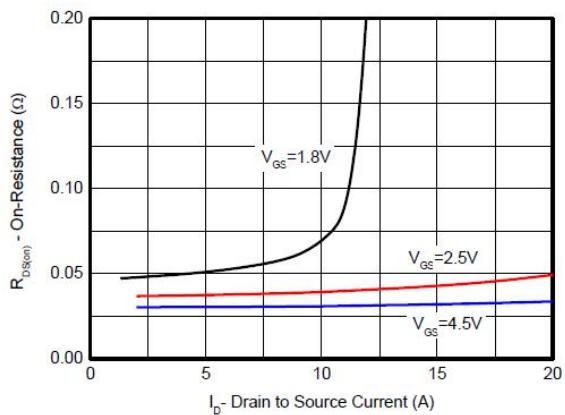
Typical Characteristics(N-Channel)



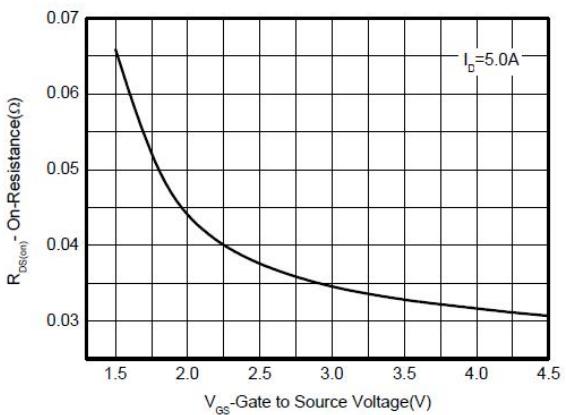
Output Characteristics



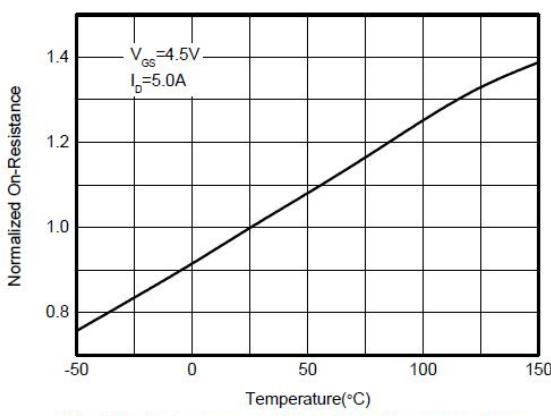
Transfer Characteristics



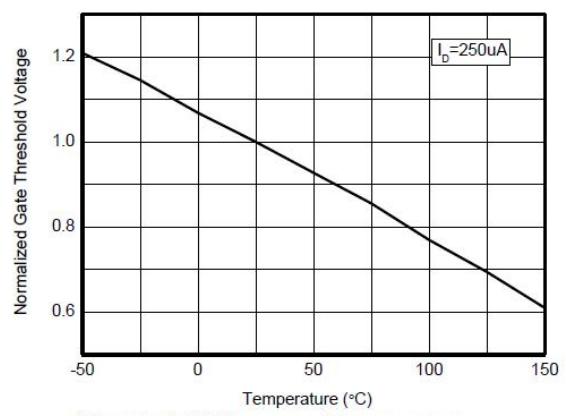
On-Resistance vs. Drain Current



On-Resistance vs. Gate-to-Source Voltage

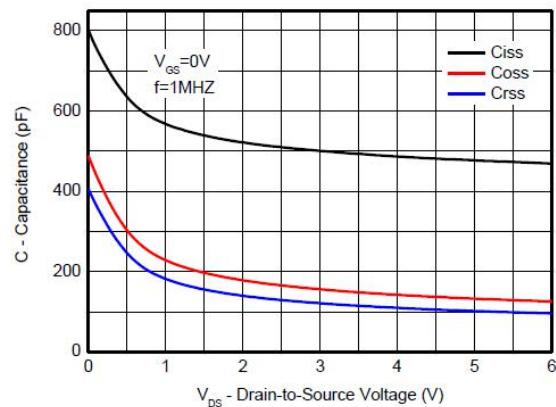


On-Resistance vs. Junction Temperature

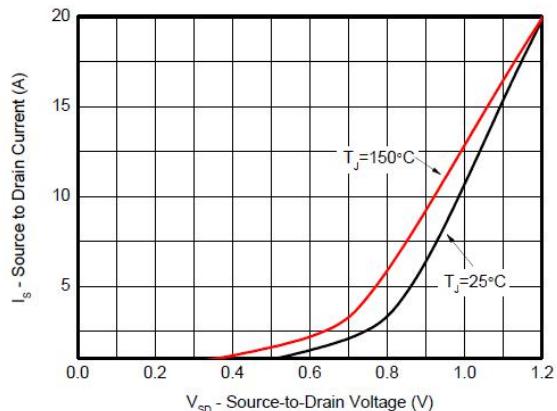


Threshold Voltage vs. Temperature

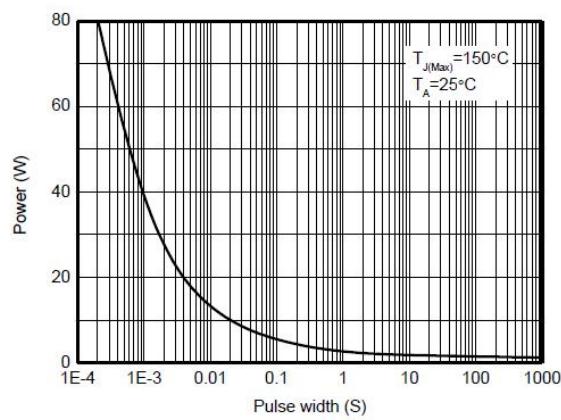
Typical Characteristics(N-Channel)



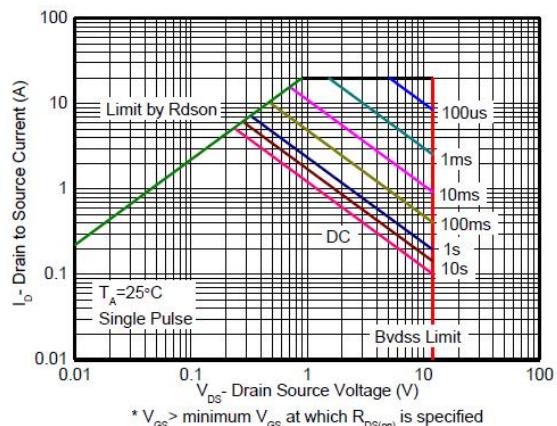
Capacitance



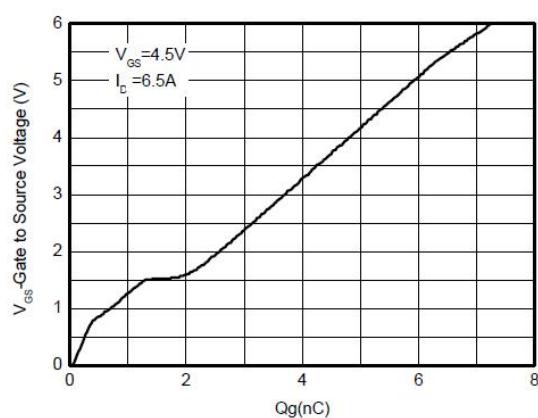
Body Diode Forward Voltage



Single pulse power

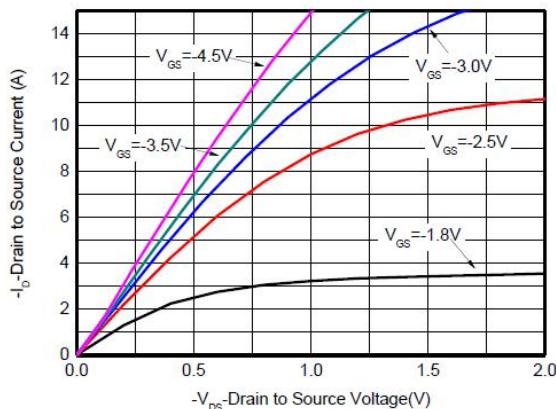


Safe operating power

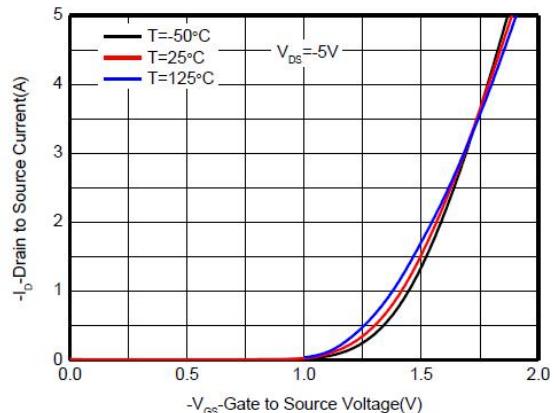


Gate charge Characteristics

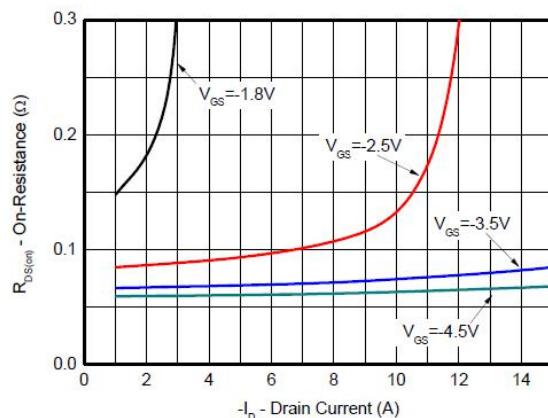
Typical Characteristics(P-Channel)



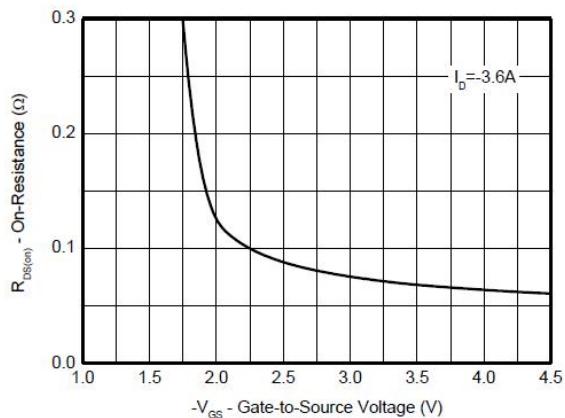
Output characteristics



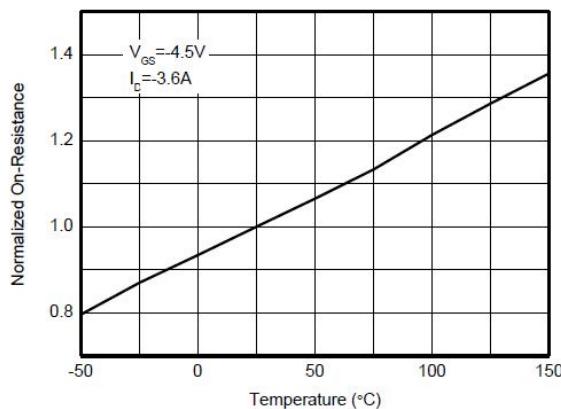
Transfer characteristics



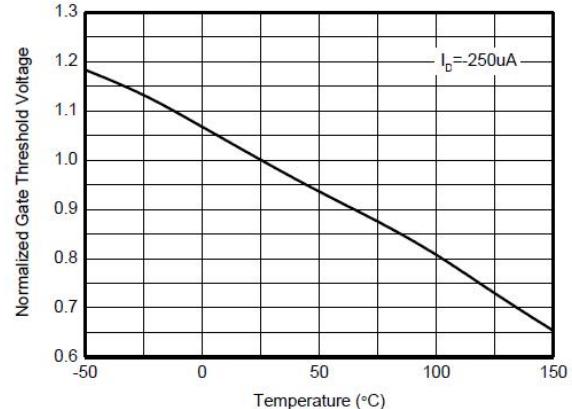
On-Resistance vs. Drain current



On-Resistance vs. Gate-to-Source voltage

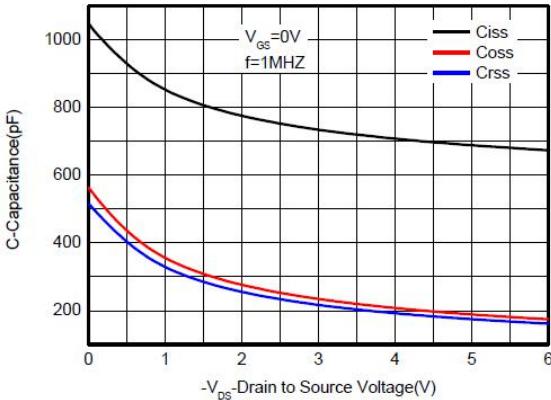


On-Resistance vs. Junction temperature

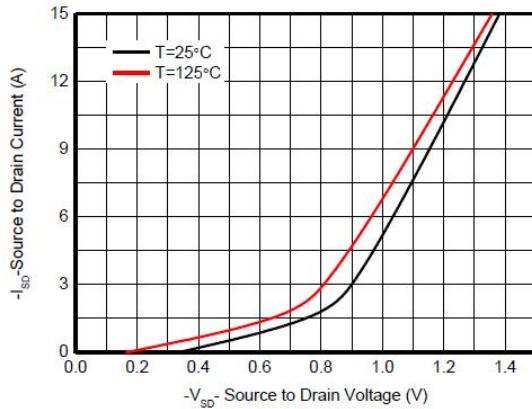


Threshold voltage vs. Temperature

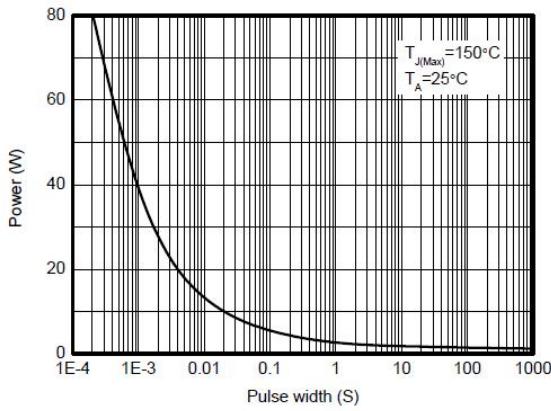
Typical Characteristics(P-Channel)



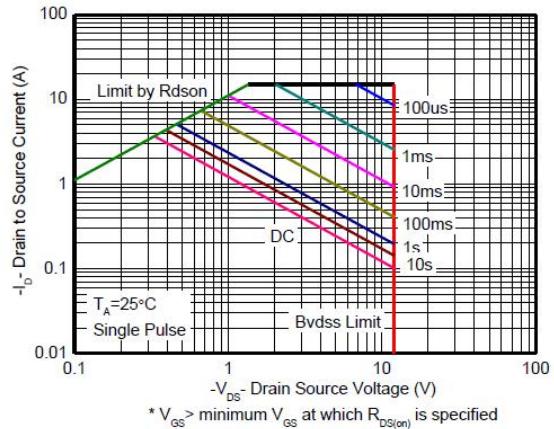
Capacitor



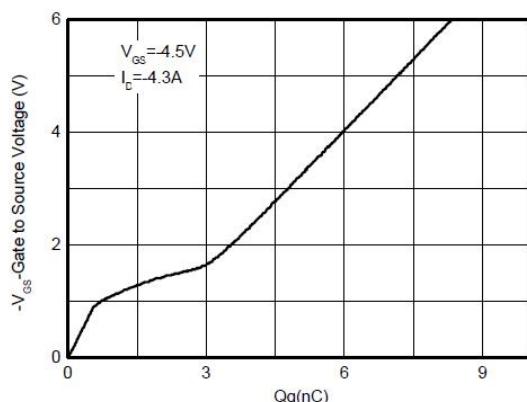
Body diode forward voltage



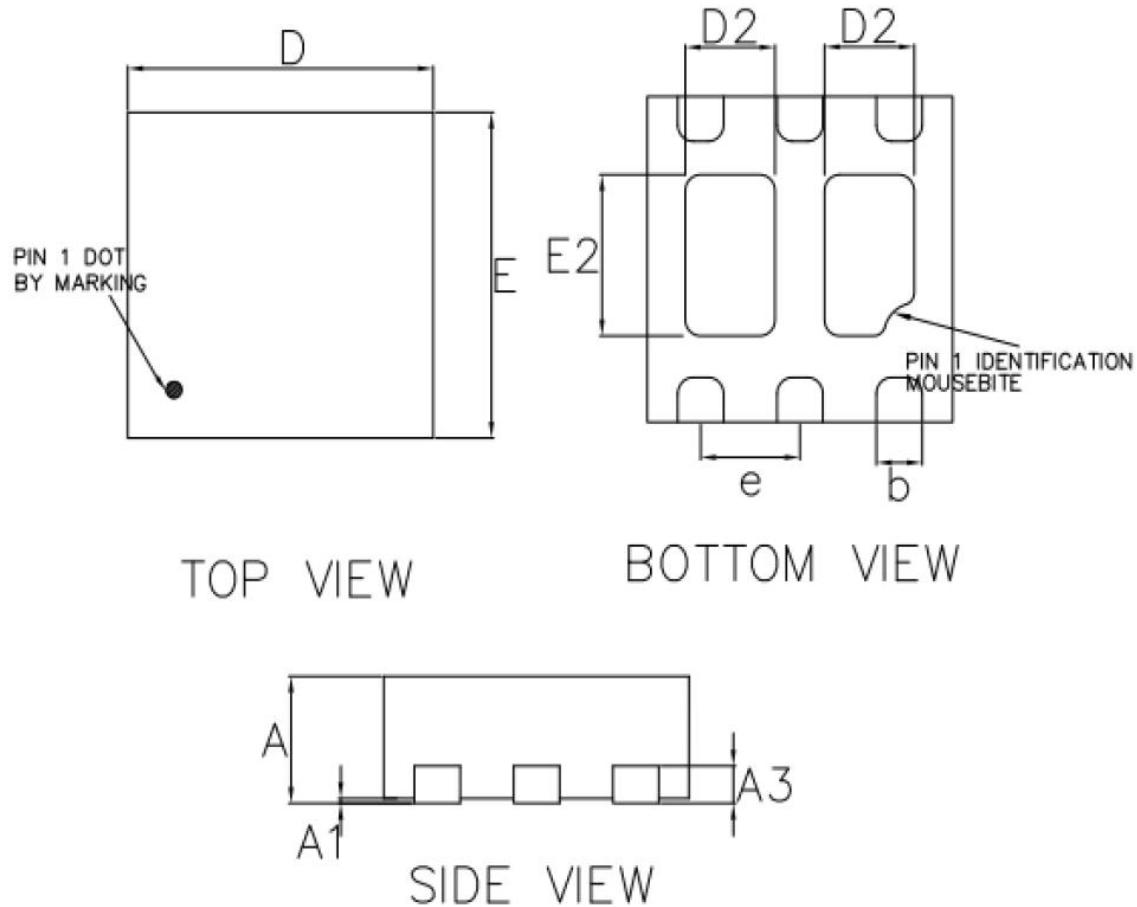
Single pulse power (Junction-to-ambient)



Safe operating power



Gate charge Characteristics

Package Outline Dimension**DFN2x2-6**

COMMON DIMENSIONS(MM)			
PKG.	W: VERY VERY THIN		
REF.	MIN.	NOM.	MAX
A	0.70	0.75	0.80
A1	0.00	—	0.05
A3	0.20 REF.		
D	1.95	2.00	2.05
E	1.95	2.00	2.05
D2	0.44	0.59	0.69
E2	0.84	0.99	1.09
b	0.25	0.30	0.35
L	0.175	0.275	0.375
e	0.65 BSC		

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